A B S T R A C T

APPARATUS FOR FABRICATING SEMICONDUCTOR WAFERS AND APPARATUS FOR THE DEPOSITION OF MATERIALS BY EVAPORATION USING A MOLECULAR BEAM

The invention relates to equipment for depositing materials by evaporation using a molecular beam (6) and to equipment for fabricating semiconductor wafers, comprising a central conveyor module (2) having a plurality of lateral ports (3) capable of functioning under vacuum pressure conditions above 10^{-8} Torr. The semiconductor wafer fabrication equipment comprises a loader module (5) and one or more substrate treatment modules (7) functioning under vacuum pressure conditions above 10^{-8} Torr, each treatment module (7) being connected to one of the ports (3) of the central conveyor module (2). According to the invention, the fabrication equipment comprises at least one module for depositing materials by evaporation using a molecular beam (6) operating under vacuum pressure conditions below 10^{-8} Torr, said molecular beam deposition module (6) being connected to one of the ports (3) of the central conveyor module (2) and being capable of receiving said substrate (1) in order to deposit a layer of materials on its face to be treated (A).